

NZ23C5V6ALT1G

24 Watt Peak Power Zener Transient Voltage Suppressors

SOT-23 Dual Common Anode Zeners for ESD Protection

This dual monolithic silicon Zener diodes is designed for applications requiring transient overvoltage protection capability. This is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. The dual junction common anode design protects two separate lines using only one package. This device is ideal for situations where board space is at a premium.

Features

- SOT-23 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- Working Peak Reverse Voltage Range – 3 V
- Standard Zener Breakdown Voltage Range – 5.6 V
- Peak Power – 24 W @ 1.0 ms (Unidirectional), per Figure 5 Waveform
- ESD Rating:
 - Class 3B (>16 kV) per the Human Body Model
 - Class C (>400 V) per the Machine Model
- Maximum Clamping Voltage @ Peak Pulse Current
- Low Leakage < 0.1 μ A
- Flammability Rating UL 94 V-0
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

Package designed for optimal automated board assembly

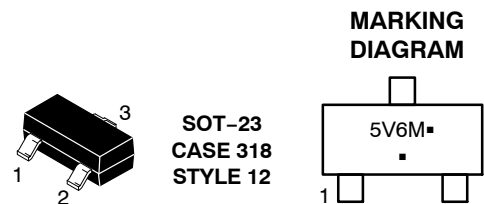
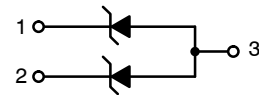
Small package size for high density applications

Available in 8 mm Tape and Reel



ON Semiconductor®

<http://onsemi.com>



SOT-23
CASE 318
STYLE 12

5V6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 1.0 ms (Note 1) @ $T_L \leq 25^\circ\text{C}$	P_{pk}	24	W
Total Power Dissipation on FR-5 Board (Note 2) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Power Dissipation on Alumina Substrate (Note 3) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Second Duration)	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

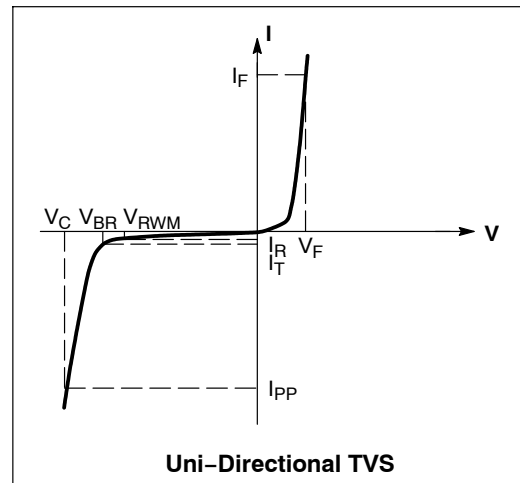
- Non-repetitive current pulse per Figure 5 and derate above $T_A = 25^\circ\text{C}$ per Figure 6.
 - FR-5 = 1.0 x 0.75 x 0.62 in.
 - Alumina = 0.4 x 0.3 x 0.024 in, 99.5% alumina.
- *Other voltages may be available upon request.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
ΘV_{BR}	Maximum Temperature Coefficient of V_{BR}
I_F	Forward Current
V_F	Forward Voltage @ I_F
Z_{ZT}	Maximum Zener Impedance @ I_{ZT}
I_{ZK}	Reverse Current
Z_{ZK}	Maximum Zener Impedance @ I_{ZK}



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

($V_F = 0.9\text{ V Max}$ @ $I_F = 10\text{ mA}$)

24 WATTS

Device	Device Marking	V_{RWM} Volts	I_R @ V_{RWM} μA	Breakdown Voltage			Max Zener Impedance (Note 5)			V_C @ I_{PP} (Note 6)		ΘV_{BR} mV/ $^\circ\text{C}$	
				V_{BR} (Note 4) (V)			Z_{ZT} @ 20mA	Z_{ZK} @ I_{ZK}	V_C	I_{PP}			
				Min	Nom	Max	@ I_T mA	Ω	Ω	mA	V		A
NZ23C5V6ALT1G	5V6	1.0	0.1	5.2	5.6	6.0	5.0	11	1600	0.25	8.0	3.0	1.26

- V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C .
- Z_{ZT} and Z_{ZK} are measured by dividing the AC voltage drop across the device by the AC current applied. The specified limits are for $I_{Z(AC)} = 0.1 I_{Z(DC)}$, with the AC frequency = 1.0 kHz.
- Surge current waveform per Figure 5 and derate per Figure 6

NZ23C5V6ALT1G

TYPICAL CHARACTERISTICS

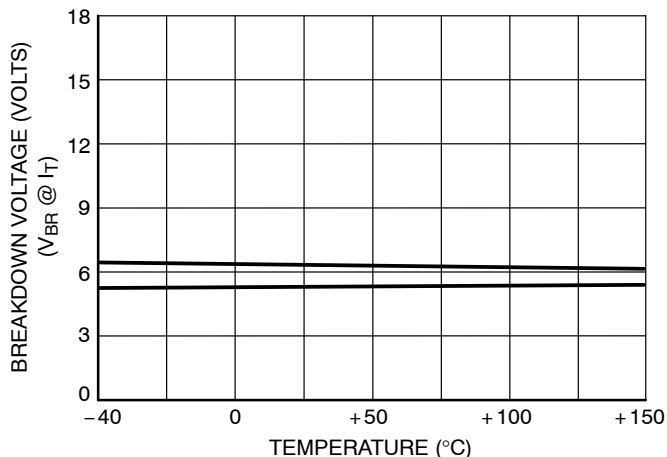


Figure 1. Typical Breakdown Voltage versus Temperature

(Upper curve is bidirectional mode, lower curve is unidirectional mode)

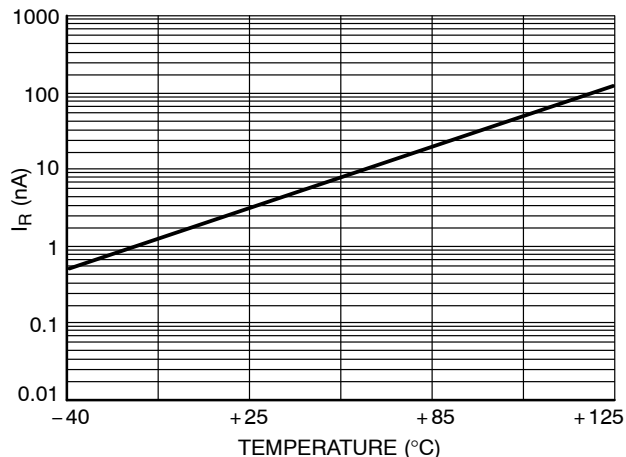


Figure 2. Typical Leakage Current versus Temperature

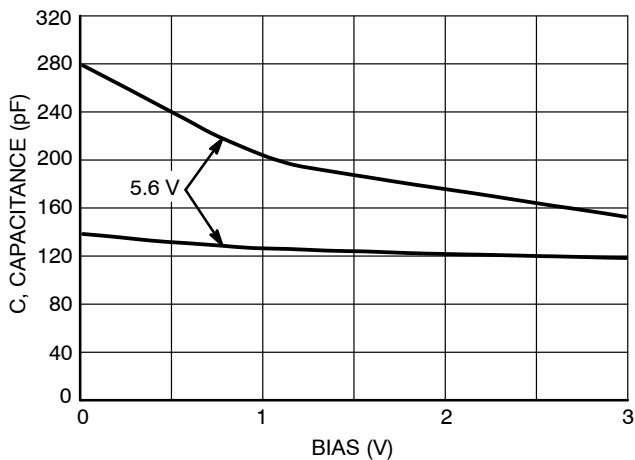


Figure 3. Typical Capacitance versus Bias Voltage

(Upper curve is unidirectional mode, lower curve is bidirectional mode)

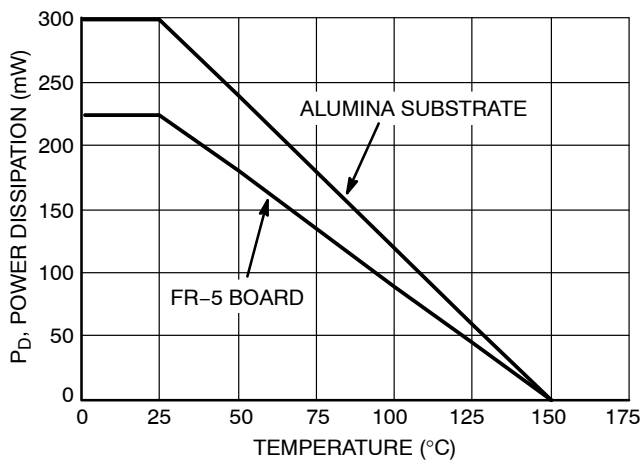


Figure 4. Steady State Power Derating Curve

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TYPICAL CHARACTERISTICS

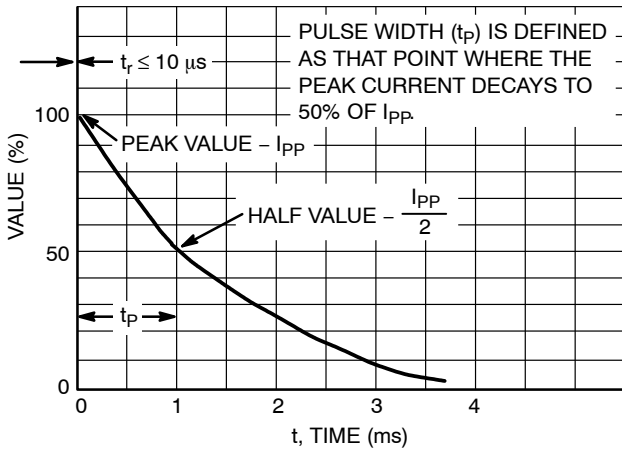


Figure 5. Pulse Waveform

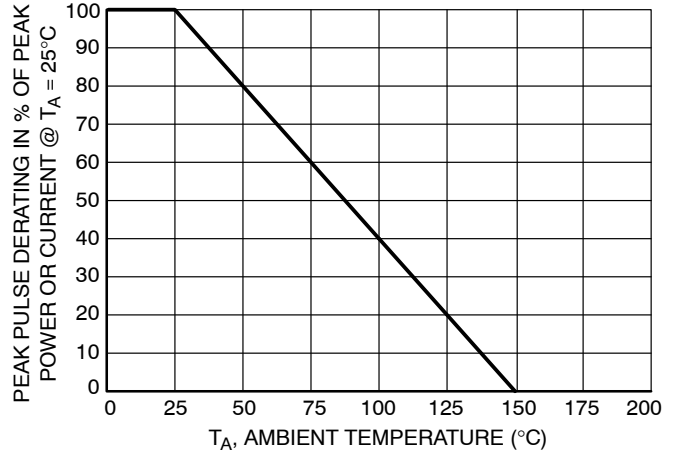


Figure 6. Pulse Derating Curve

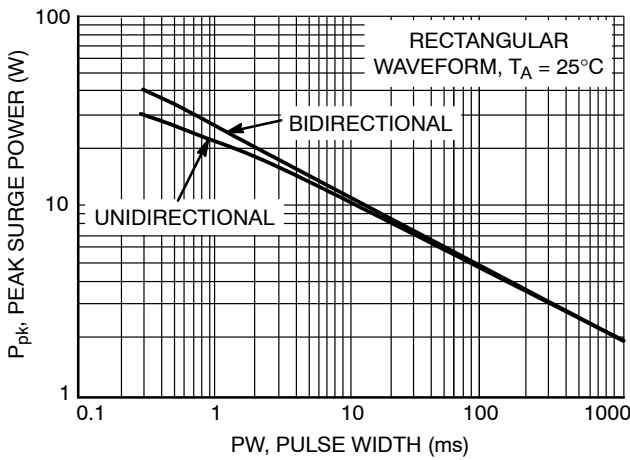


Figure 7. Maximum Non-repetitive Surge Power, P_{pk} versus PW

Power is defined as $V_{RSM} \times I_{Z(pk)}$ where V_{RSM} is the clamping voltage at $I_{Z(pk)}$.

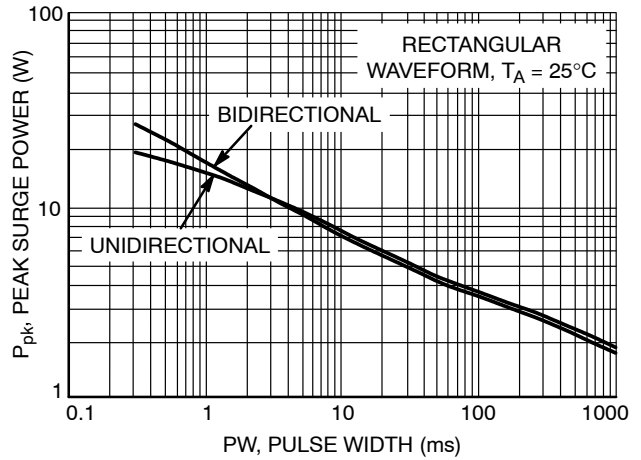


Figure 8. Maximum Non-repetitive Surge Power, $P_{pk(NOM)}$ versus PW

Power is defined as $V_Z(NOM) \times I_{Z(pk)}$ where $V_Z(NOM)$ is the nominal Zener voltage measured at the low test current used for voltage classification.

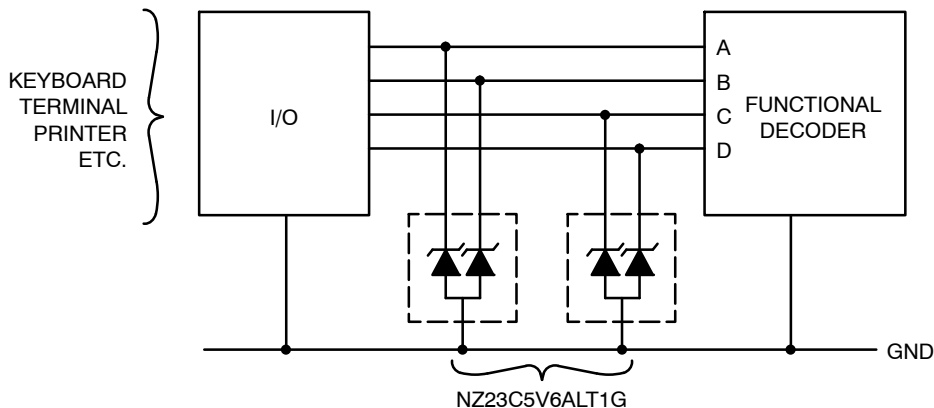
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TYPICAL COMMON ANODE APPLICATIONS

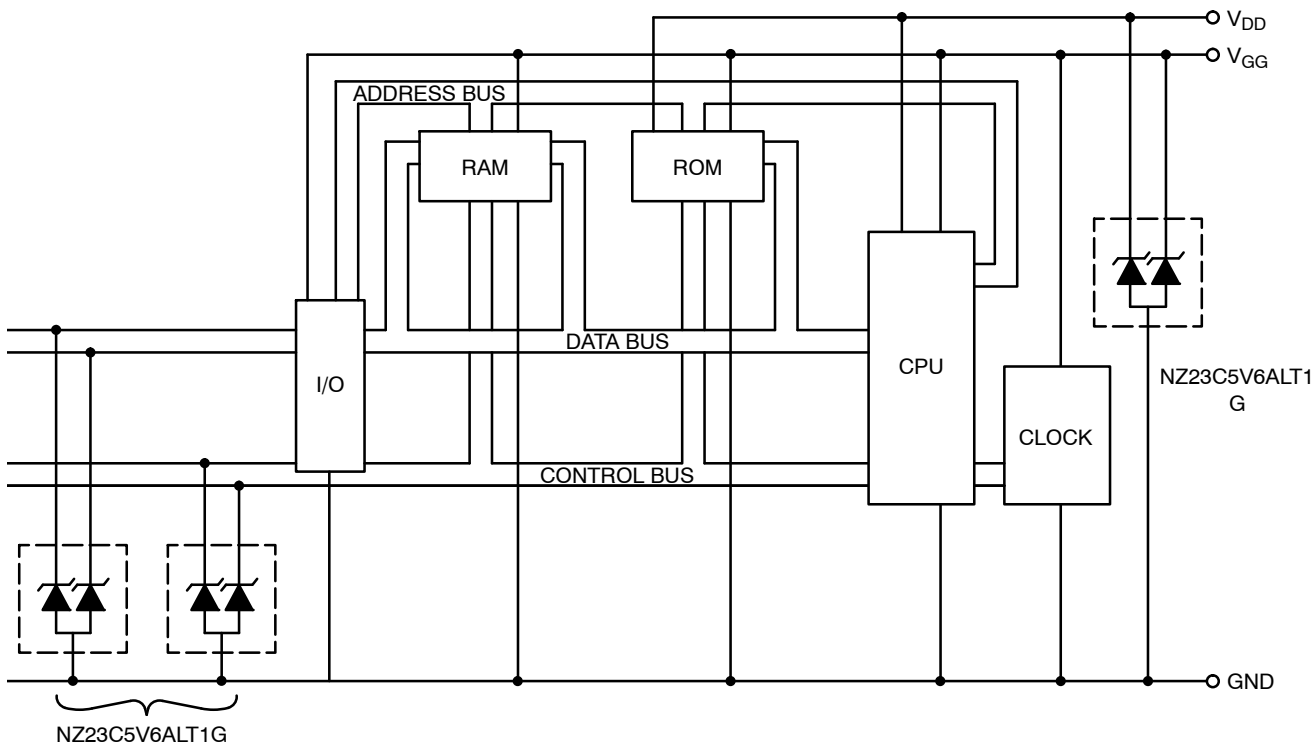
A quad junction common anode design in a SOT-23 package protects four separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. Two simplified examples of TVS applications are illustrated below.

Computer Interface Protection



Microprocessor Protection



NZ23C5V6ALT1G

ORDERING INFORMATION

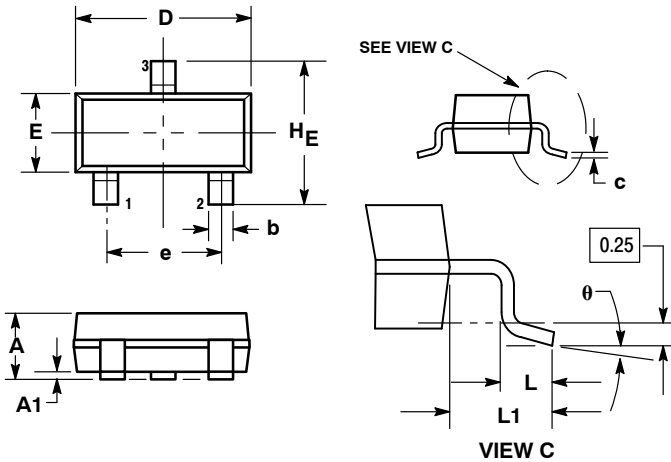
Device	Package	Shipping [†]
NZ23C5V6ALT1G	SOT-23 (Pb-Free)	3000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NZ23C5V6ALT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AN



NOTES:

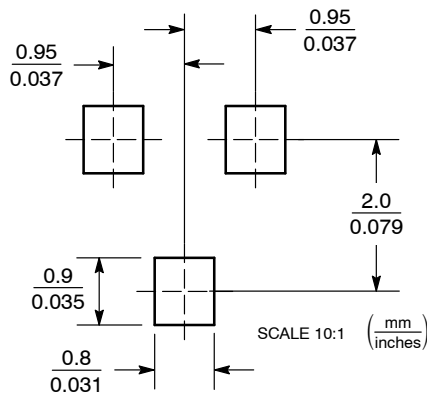
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 12:

1. CATHODE
2. CATHODE
3. ANODE

SOLDERING FOOTPRINT



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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